

Notice of References Cited	Application/Control No. 10/051,886		Applicant(s)/Patent Under Reexamination FELMETSGER, VALERY V.	
	Examiner Alonzo Chambliss		Art Unit 2814	Page 1 of 1

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	C	US-6,294,444	09-2001	Ueno, Katsunori	438/514
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	V	D.B. Beach, " Design of low-temperature thermal chemical vapor deposition processes ", IBM J. REs. Develop., November 1990, Vol. 34, No. 6,
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	X	Valery Felmetzger, " Stress Control in multi-Layer Backside Metallization of Thinned Wafers ", October 1999, Sputtered Films, Inc., pages 1-15.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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